

ABSTRACT OF THE DISCLOSURE

A method is provided for using a three-dimensional, Pi-shaped, woven preform to assemble first and second composite components. The preform is infused with resin, and at least one surface of the preform is adhered to at least one surface of the first component using a film adhesive. The preform is cured while an oversized tool coated with non-stick material is located within a clevis formed by two legs of the preform. A removable peel ply is located between the tool and the clevis, and semi-rigid over-presses are used during curing. After curing, the tool, over-presses, and peel ply are removed, and adhesive is injected into the clevis. The second component is inserted into the clevis, the adhesive adhering to an inner surface of the clevis and to at least one surface of the second component for retaining the second component within the clevis, the second component having a smaller width than the tool.